

CD4011A, CD4012A, CD4023A Types

CMOS NAND Gates

Quad 2 Input – CD4011A
Dual 4 Input – CD4012A
Triple 3 Input – CD4023A

The TI-CD4011A, CD4012A, and CD-4023A NAND gates provide the system designer with direct implementation of the NAND function and supplement the existing family of CMOS gates.

These types are supplied in 14-lead hermetic dual-in-line ceramic packages (D and F suffixes), 14-lead dual-in-line plastic packages (E suffix), 14-lead ceramic flat packages (K suffix), and in chip form (H suffix).

Features:

- Quiescent current specified to 15 μ A
- Maximum input leakage of 1 μ A at 15 V (full package-temperature range)
- 1-V noise margin (full package-temperature range)

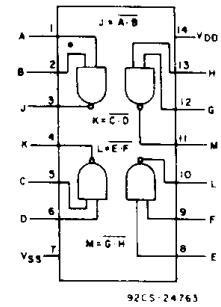
RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

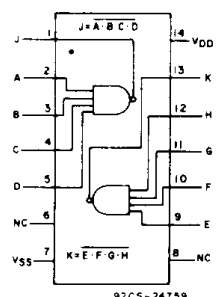
Characteristic	Min.	Max.	Units
Supply Voltage Range (over full package temperature range)	3	12	V

MAXIMUM RATINGS, Absolute-Maximum Values:

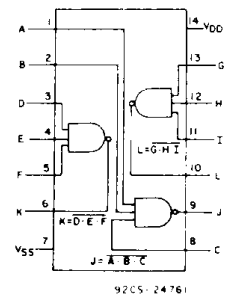
STORAGE-TEMPERATURE RANGE (T_{stg}) -65 to +150°C
 OPERATING-TEMPERATURE RANGE (T_A):
 PACKAGE TYPES D, F, K, H -55 to +125°C
 PACKAGE TYPE E -40 to +85°C
 DC SUPPLY-VOLTAGE RANGE, (V_{DD})
 (Voltages referenced to V_{SS} Terminal) -0.5 to +15 V
 POWER DISSIPATION PER PACKAGE (P_D):
 FOR $T_A = -40$ to +60°C (PACKAGE TYPE E) 500 mW
 FOR $T_A = +60$ to +85°C (PACKAGE TYPE E) Derate Linearly at 12 mW/°C to 200 mW
 FOR $T_A = -55$ to +100°C (PACKAGE TYPES D, F, K) 500 mW
 FOR $T_A = +100$ to +125°C (PACKAGE TYPES D, F, K) Derate Linearly at 12 mW/°C to 200 mW
 DEVICE DISSIPATION PER OUTPUT TRANSISTOR
 FOR $T_A =$ FULL PACKAGE-TEMPERATURE RANGE (ALL PACKAGE TYPES) 100 mW
 INPUT VOLTAGE RANGE, ALL INPUTS -0.5 to $V_{DD} + 0.5$ V
 LEAD TEMPERATURE (DURING SOLDERING):
 At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79 mm) from case for 10 s max. +265°C



CD4011A



CD4012A



CD4023AH

Fig. 1 – Functional diagrams.

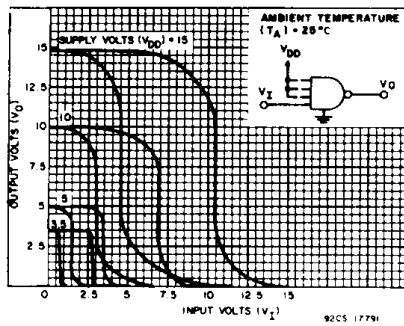
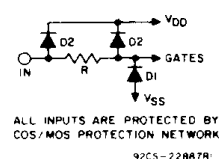


Fig. 2 – Minimum & maximum voltage transfer characteristics.

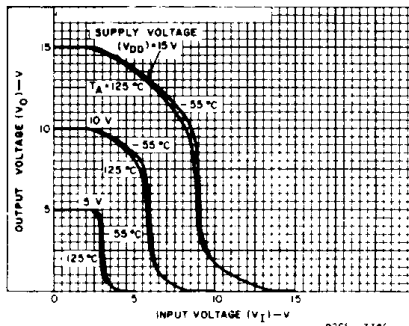


Fig. 3 – Typical voltage transfer characteristics as a function of temperature.

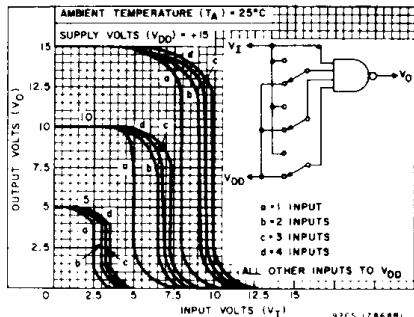


Fig. 4 – Typical multiple input switching transfer characteristics for CD4012A.

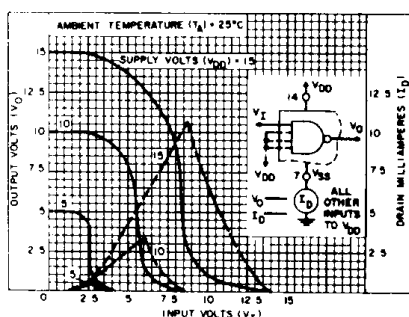


Fig. 5 – Typical current & voltage transfer characteristics.

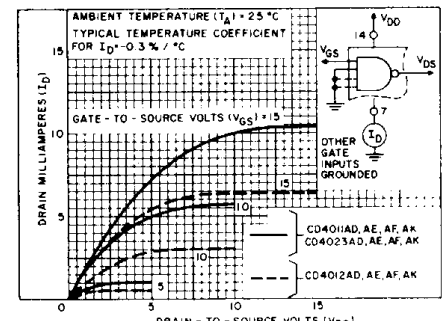


Fig. 6 – Typical n-channel drain characteristics.

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STATIC ELECTRICAL CHARACTERISTICS

Characteristic	Conditions			Limits at Indicated Temperatures (°C)								Units
	V _O (V)	V _{IN} (V)	V _{DD} (V)	D, F, K, H Packages				E Package				
				-55	+25		+125	-40	+25		+85	
Quiescent Device Current, I _L Max.	-	-	5	0.05	0.001	0.05	3	0.5	0.005	0.5	15	μA
	-	-	10	0.1	0.001	0.1	6	5	0.005	5	30	
	-	-	15	2	0.02	2	40	50	0.5	50	500	
Output Voltage: Low-Level V _{OL}	-	0, 5	5	0 Typ.; 0.05 Max.								V
High Level, V _{OH}	-	0, 10	10	4.95 Min.; 5 Typ.								
	-	0, 10	10	9.95 Min.; 10 Typ.								
Noise Immunity: Inputs Low, V _{NL}	3.6	-	5	1.5 Min.; 2.25 Typ.								V
Inputs High, V _{NH}	7.2	-	10	3 Min.; 4.5 Typ.								
Noise Margin: Inputs Low, V _{NML}	1.4	-	5	1.5 Min.; 2.25 Typ.;								
Inputs High, V _{NMH}	2.8	-	10	3 Min.; 4.5 Typ.								
Output Drive Current: N-Channel (Sink) I _{DN} Min.												mA
CD4011A	0.5	-	5	0.31	0.5	0.25	0.175	0.145	0.5	0.12	0.095	
CD4023A	0.5	-	10	0.62	0.6	0.5	0.35	0.3	0.6	0.25	0.2	
CD4012A	0.5	-	5	0.15	0.25	0.12	0.085	0.072	0.25	0.06	0.05	
	0.5	-	10	0.31	0.6	0.25	0.175	0.155	0.6	0.13	0.105	
P-Channel (Source) I _{DP} Min. All Types	4.5	-	5	-0.31	-0.5	-0.25	-0.175	-0.145	-0.5	-0.12	-0.095	
	9.5	-	10	-0.75	-1.2	-0.6	-0.4	-0.35	-1.2	-0.3	-0.24	
Input Leakage Current, I _{IL} , I _{IH}	Any Input		15	±10 ⁻⁵ Typ.; ±1 Max.								μA

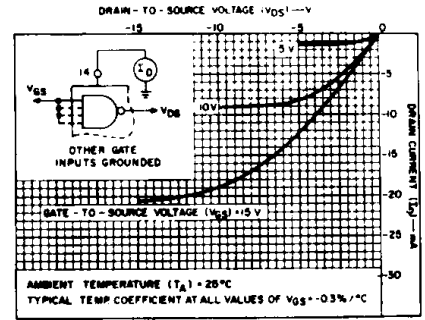


Fig. 7 - Typical p-channel drain characteristics.

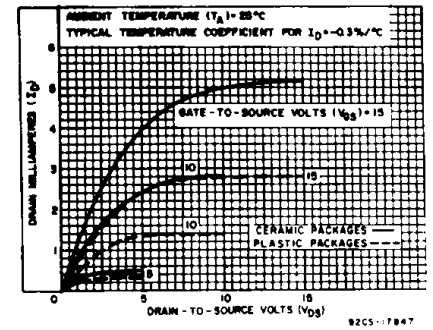


Fig. 8 - Minimum n-channel drain characteristics - CD4011A & CD4023A.

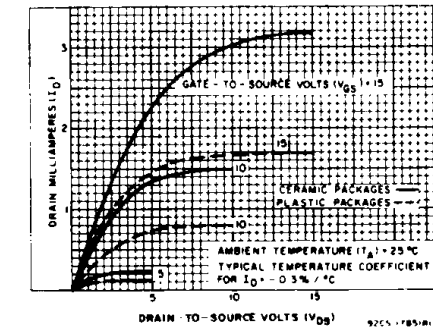


Fig. 9 - Minimum n-channel drain characteristics.

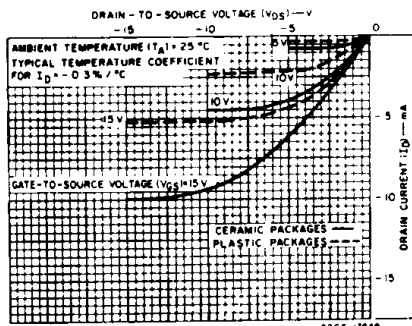


Fig. 10 - Minimum p-channel drain characteristics.

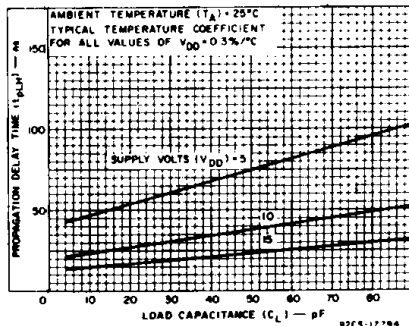


Fig. 11 - Typical low-to-high level propagation delay time vs. C_L.

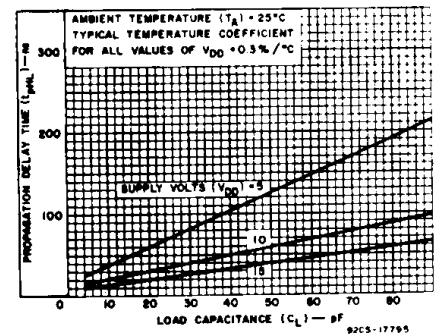


Fig. 12 - Typical high-to-low level propagation delay time vs. C_L - CD4011A, & CD4023A.

CD4011A, CD4012A, CD4023A Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, $C_L = 15\text{ pF}$, Input $t_r, t_f = 20\text{ ns}$, $R_L = 200\text{ k}\Omega$

CHARACTERISTICS	TEST CONDITIONS	LIMITS				UNITS	
		D, F, K, H Packages		E Package			
		V _{DD} (V)	Typ.	Max.	Typ.		Max.
Propagation Delay Time: Low-to-High Level, t_{PLH}		5	50	75	50	100	ns
		10	25	40	25	50	
High-to-Low Level, t_{PHL} CD4011A and CD4023A		5	50	75	50	100	ns
		10	25	40	25	50	
CD4012A		5	100	150	100	200	ns
		10	50	75	50	100	
Transition Time: Low-to-High Level, t_{TLH}		5	75	100	75	125	ns
		10	40	60	40	75	
High-to-Low Level, t_{THL} CD4011A and CD4023A		5	75	125	75	150	ns
		10	50	75	50	100	
CD4012A		5	250	375	250	500	ns
		10	125	200	125	250	
Input Capacitance, C_i	Any Input	5	—	5	—	—	pF

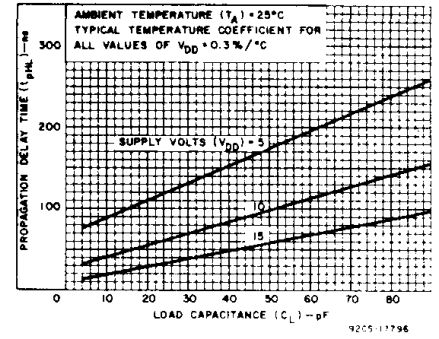


Fig. 13 — Typical high-to-low level propagation delay time vs. C_L — CD4012A.

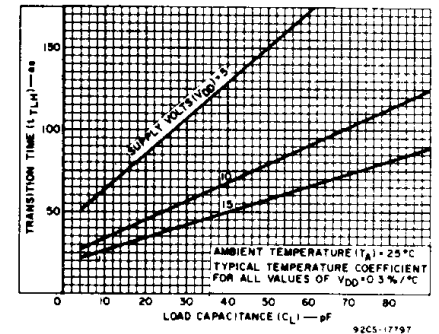


Fig. 14 — Typical low-to-high transition time vs. C_L .

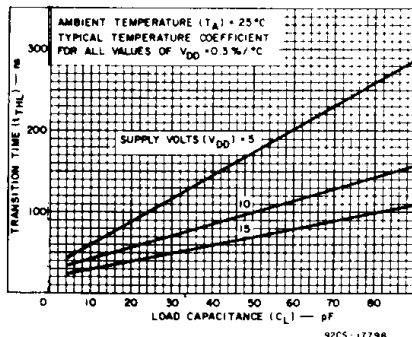


Fig. 15 — Typical high-to-low level transition time vs. C_L — CD4011A & CD4023A.

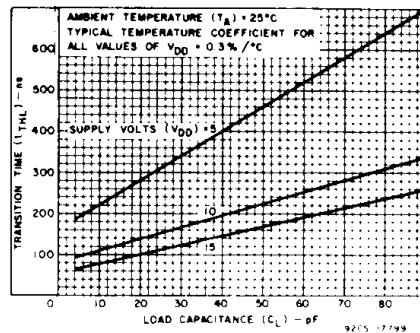


Fig. 16 — Typical high-to-low level transition time vs. C_L — CD4012A.

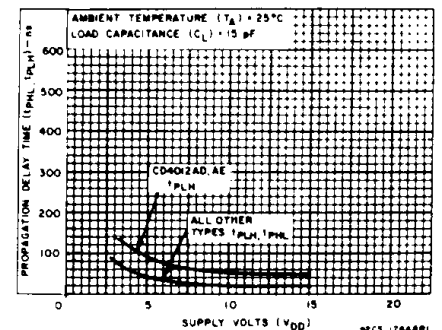


Fig. 17 — Minimum propagation delay time vs. V_{DD} .

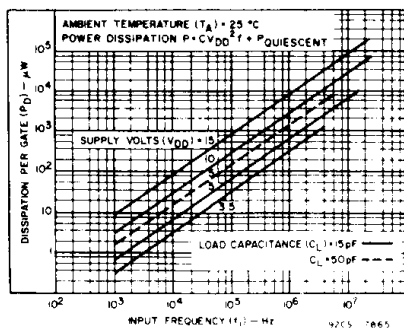


Fig. 18 — Typical dissipation characteristics.

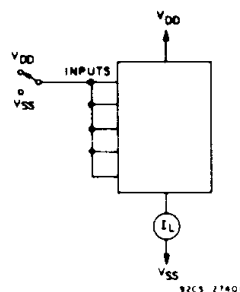


Fig. 19 — Quiescent device current test circuit.

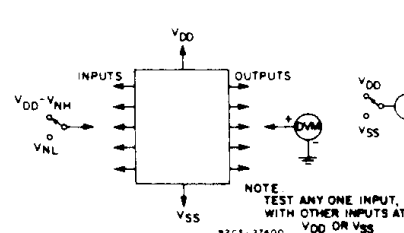


Fig. 20 — Noise immunity test circuit.

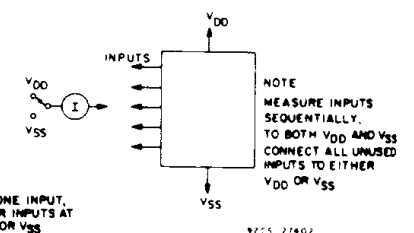


Fig. 21 — Input leakage current test circuit.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4011AD3	ACTIVE	CDIP SB	JD	14	1	TBD	POST-PLATE	N / A for Pkg Type
CD4023AFB	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/05001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/05003BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
M/05003BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

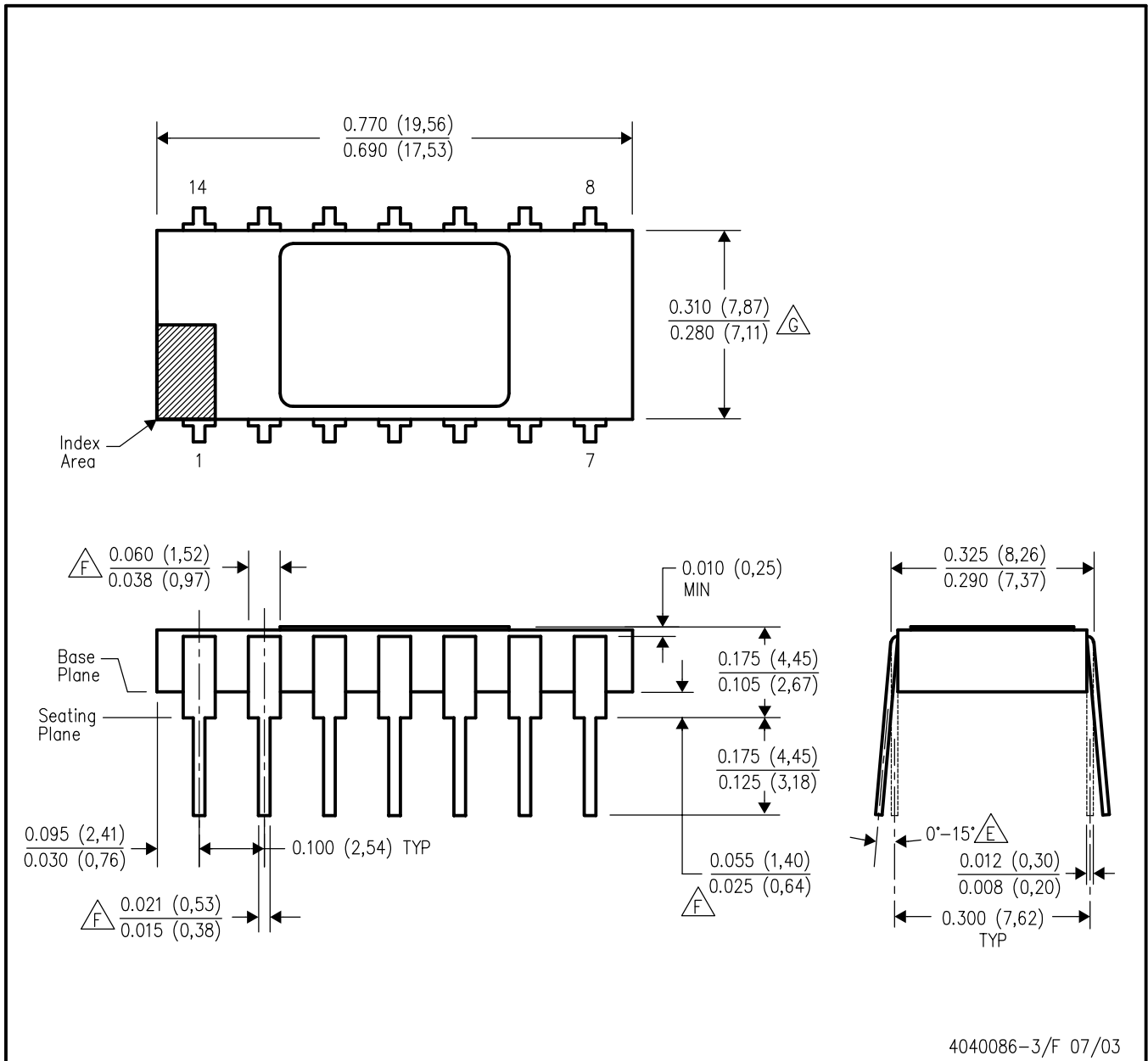


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

JD (R-CDIP-T14)

CERAMIC SIDE-BRAZE DUAL-IN-LINE



4040086-3/F 07/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Controlling dimension: inch.
 - D. Leads within 0.005 (0,13) radius of true position (TP) at gage plane with maximum material condition and unit installed.
 - E. Angle applies to spread leads prior to installation.
 - F. Outlines on which the seating plane is coincident with the plane (standoff = 0), terminals lead standoffs are not required, and lead shoulder may equal lead width along any part of the lead above the seating/base plane.
 - G. Body width does not include particles of packing materials.
 - H. A visual index feature must be located within the cross-hatched area.

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